

# PMEG045V150EPD

45 V, 15 A low VF MEGA Schottky barrier rectifier

8 September 2016

**Product data sheet** 

### 1. General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a CFP15 (SOT1289) power and flat lead Surface-Mounted Device (SMD) plastic package.

### 2. Features and benefits

- Average forward current: I<sub>F(AV)</sub> ≤ 15 A
- Reverse voltage: V<sub>R</sub> ≤ 45 V
- · Extremely low forward voltage
- · High power capability due to clip-bonding technology and heat sink
- · Small and thin SMD power plastic package, typical height 0.78 mm
- AEC-Q101 qualified

## 3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- · Switch mode power supply
- Freewheeling application
- Reverse polarity protection
- Low power consumption application

### 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I <sub>F(AV)</sub>	average forward current	square wave; $\delta$ = 0.5 ; f = 20 kHz; T <sub>sp</sub> ≤ 160 °C	-	-	15	Α
$V_R$	reverse voltage	T <sub>j</sub> = 25 °C	-	-	45	V
V <sub>F</sub>	forward voltage	$I_F$ = 15 A; $t_p \le 300 \ \mu s$ ; δ ≤ 0.02 ; $T_j$ = 25 °C; pulsed	-	430	490	mV
I <sub>R</sub>	reverse current	$V_R$ = 10 V; $t_p \le 3$ ms; $T_j$ = 25 °C; $\delta \le$ 0.3 ; pulsed	-	30	70	μΑ
		$V_R$ = 45 V; $t_p \le 3$ ms; $T_j$ = 25 °C; $\delta \le$ 0.3 ; pulsed	-	260	900	μΑ



## 5. Pinning information

#### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	Α	anode		⊬ <mark>B</mark> I □ A
2	Α	anode	3	A aaa-009063
3	K	cathode	2 CFP15 (SOT1289)	

## 6. Ordering information

#### **Table 3. Ordering information**

Type number	Package				
	Name	Description	Version		
PMEG045V150EPD	CFP15	plastic, thermal enhanced ultra thin SMD package; 3 leads; body: 5.8 x 4.3 x 0.78 mm	SOT1289		

## 7. Marking

#### **Table 4. Marking codes**

Type number	Marking code
PMEG045V150EPD	045V 150E

## 8. Limiting values

#### Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_R$	reverse voltage	T <sub>j</sub> = 25 °C		-	45	V
I <sub>F</sub>	forward current	T <sub>sp</sub> = 155 °C; δ = 1		-	21	Α
I <sub>F(AV)</sub>	average forward current	square wave; $\delta$ = 0.5 ; f = 20 kHz; $T_{sp} \le$ 160 °C		-	15	А
I <sub>FSM</sub>	non-repetitive peak forward current	square wave; $t_p$ = 8 ms; $T_{j(init)}$ = 25 °C		-	270	Α
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	[1]	-	1.66	W
			[2]	-	2.15	W
			[3]	-	3.75	W
Tj	junction temperature			-	175	°C
T <sub>amb</sub>	ambient temperature			-55	175	°C
T <sub>stg</sub>	storage temperature			-65	175	°C

Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint. Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1  $\rm cm^2$ . [2] [3]

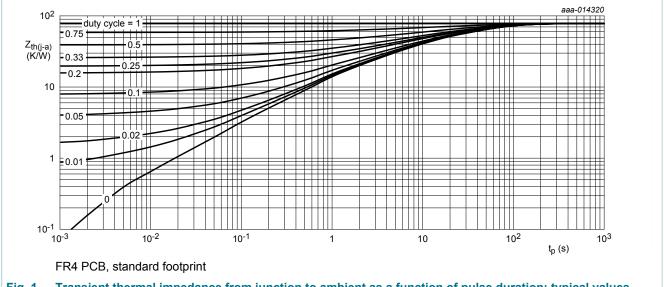
Device mounted on a ceramic Printed-Circuit Board (PCB), Al<sub>2</sub>O<sub>3</sub>, standard footprint.

### 9. Thermal characteristics

**Table 6. Thermal characteristics** 

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
R <sub>th(j-a)</sub>	thermal resistance	in free air	[1][2]	-	-	90	K/W
	from junction to ambient		[1][3]	-	-	70	K/W
			[1][4]	-	-	40	K/W
R <sub>th(j-sp)</sub>	thermal resistance from junction to solder point		<u>[5]</u>	-	-	3	K/W

- For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P<sub>R</sub> are a significant part of the total power losses.
- Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.
- [5] Soldering point of cathode tab.



Transient thermal impedance from junction to ambient as a function of pulse duration; typical values Fig. 1.

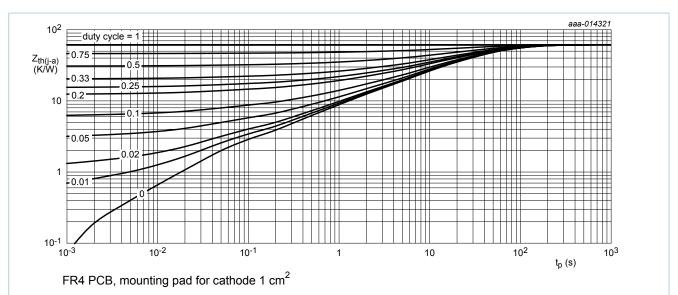


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

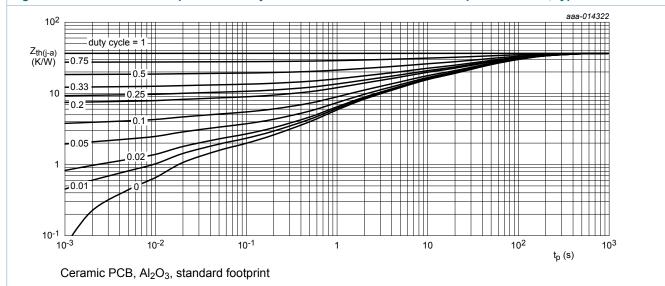
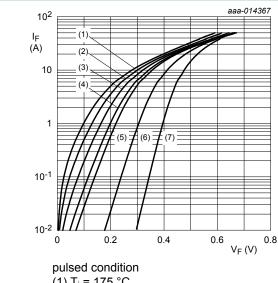


Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

### 10. Characteristics

#### **Table 7. Characteristics**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$V_{(BR)R}$	reverse breakdown voltage	$I_R$ = 5 mA; $T_j$ = 25 °C; $t_p$ ≤ 1.2 ms; δ ≤ 0.12; pulsed	45	-	-	V
$V_{F}$	forward voltage	$I_F$ = 1 A; $t_p \le 300 \ \mu s$ ; δ ≤ 0.02 ; $T_j$ = 25 °C; pulsed	-	305	350	mV
		$I_F$ = 5 A; $t_p \le 300 \mu s$ ; δ ≤ 0.02 ; $T_j$ = 25 °C; pulsed	-	360	410	mV
		$I_F$ = 10 A; $t_p \le 300 \ \mu s$ ; δ ≤ 0.02 ; $T_j$ = 25 °C; pulsed	-	400	-	mV
		$I_F$ = 15 A; $t_p \le 300 \ \mu s$ ; δ ≤ 0.02 ; $T_j$ = 25 °C; pulsed	-	430	490	mV
		$I_F$ = 15 A; $t_p \le 300 \mu s$ ; δ ≤ 0.02 ; $T_j$ = 125 °C; pulsed	-	370	-	mV
I <sub>R</sub>	reverse current	$V_R = 5 \text{ V}; t_p \le 3 \text{ ms}; T_j = 25 \text{ °C}; \delta \le 0.3 \text{ ; pulsed}$	-	20	-	μA
		$V_R = 10 \text{ V}; t_p \le 3 \text{ ms}; T_j = 25 \text{ °C}; \delta \le 0.3 \text{ ; pulsed}$	-	30	70	μA
		$V_R = 30 \text{ V}; t_p \le 3 \text{ ms}; T_j = 25 \text{ °C}; \delta \le 0.3 \text{ ; pulsed}$	-	90	-	μA
		$V_R = 45 \text{ V}; t_p \le 3 \text{ ms}; T_j = 25 \text{ °C}; \delta \le 0.3 \text{ ; pulsed}$	-	260	900	μA
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 1 V; f = 1 MHz; T <sub>j</sub> = 25 °C	-	1870	-	pF
		V <sub>R</sub> = 10 V; f = 1 MHz; T <sub>j</sub> = 25 °C	-	610	-	pF
t <sub>rr</sub>	reverse recovery time step recovery	$I_F = 0.5 \text{ A}; I_R = 0.5 \text{ A}; I_{R(meas)} = 0.1 \text{ A};$ $T_j = 25 ^{\circ}\text{C}$	-	54	-	ns
	reverse recovery time ramp recovery	$dI_F/dt = 200 \text{ A/}\mu\text{s}; T_j = 25 ^{\circ}\text{C}; I_F = 6 \text{ A}; V_R = 26 \text{ V}$	-	19	-	ns
$V_{FRM}$	peak forward recovery voltage	$I_F = 0.5 \text{ A}; dI_F/dt = 20 \text{ A/}\mu\text{s}; T_j = 25 °\text{C}$	-	294	-	mV



(1)  $T_i = 175 \,^{\circ}C$ 

(2)  $T_i = 150 \, ^{\circ}\text{C}$ 

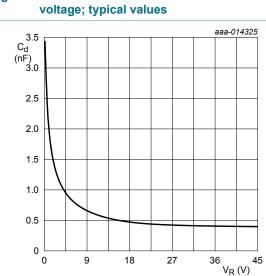
(3)  $T_j = 125 \,^{\circ}\text{C}$ 

(4)  $T_j = 100 \, ^{\circ}C$ 

(5)  $T_j = 85 \,^{\circ}C$ (6)  $T_i = 25 \,^{\circ}\text{C}$ 

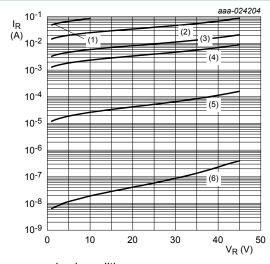
 $(7) T_i = -40 ^{\circ}C$ 

Fig. 4. Forward current as a function of forward



f = 1 MHz;  $T_{amb} = 25 \text{ °C}$ 

Fig. 6. Diode capacitance as a function of reverse voltage; typical values



pulsed condition

(1)  $T_j = 150 \, ^{\circ}C$ 

(2)  $T_i = 125 \,^{\circ}\text{C}$ 

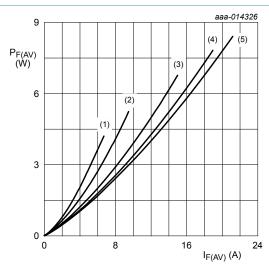
(3)  $T_{j}^{'} = 100 \, ^{\circ}\text{C}$ 

(4)  $T_j = 85 \, ^{\circ}C$ 

(5)  $T_j = 25 \,^{\circ}\text{C}$ 

(6)  $T_i = -40 \,^{\circ}\text{C}$ 

Fig. 5. Reverse current as a function of reverse voltage; typical values



T<sub>i</sub> = 100 °C

 $(1) \delta = 0.1$ 

 $(2) \delta = 0.2$ 

 $(3) \delta = 0.5$ 

 $(4) \delta = 0.8$  $(5) \delta = 1$ 

Fig. 7. Average forward power dissipation as a function of average forward current; typical values

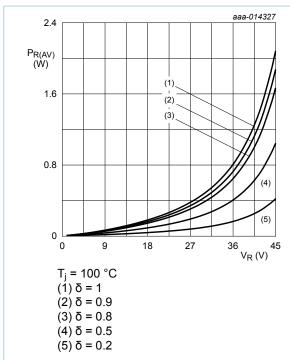
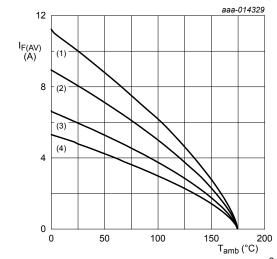


Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

 $T_j = 175 \,{}^{\circ}\text{C}$ 

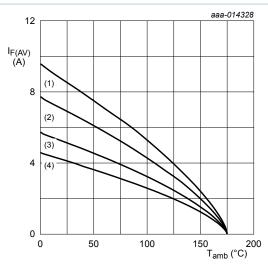
 $(1) \delta = 1; DC$ 

(2)  $\delta$  = 0.5; f = 20 kHz

(3)  $\delta$  = 0.2; f = 20 kHz

(4)  $\delta$  = 0.1; f = 20 kHz

Fig. 10. Average forward current as a function of ambient temperature; typical values



FR4 PCB, standard footprint

 $T_i = 175 \,{}^{\circ}\text{C}$ 

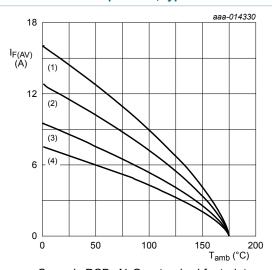
 $(1) \delta = 1; DC$ 

(2)  $\delta$  = 0.5; f = 20 kHz

(3)  $\delta$  = 0.2; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint

T<sub>i</sub> = 175 °C

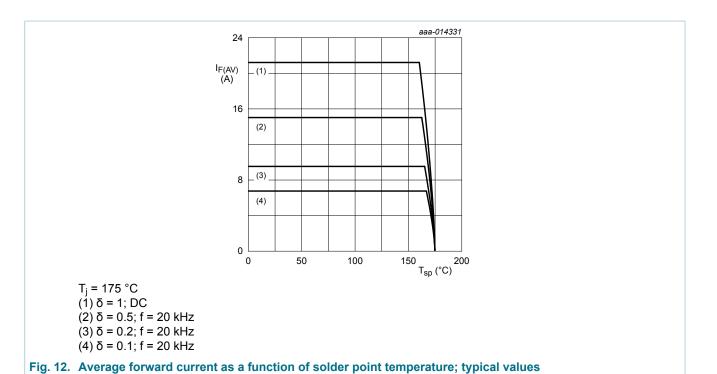
 $(1) \delta = 1; DC$ 

(2)  $\delta$  = 0.5; f = 20 kHz

(3)  $\delta$  = 0.2; f = 20 kHz

(4)  $\delta$  = 0.1; f = 20 kHz

Fig. 11. Average forward current as a function of ambient temperature; typical values



## 11. Test information

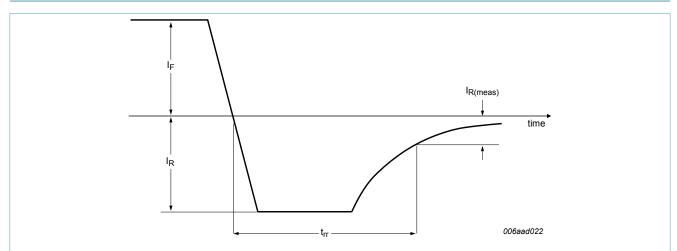


Fig. 13. Reverse recovery definition; step recovery

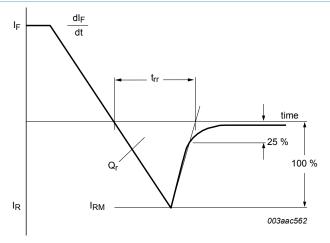


Fig. 14. Reverse recovery definition; ramp recovery

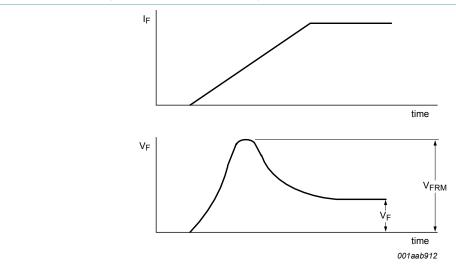
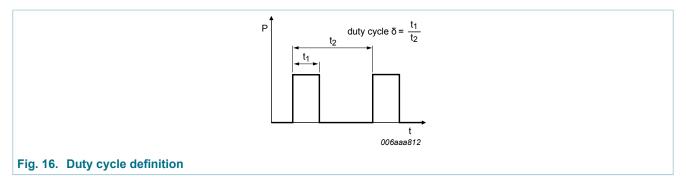


Fig. 15. Forward recovery definition

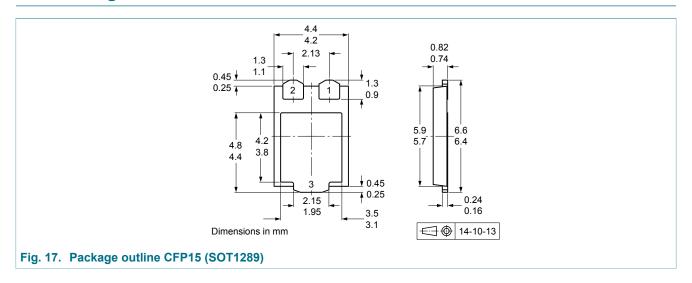


The current ratings for the typical waveforms are calculated according to the equations:  $I_{F(AV)} = I_{M} \times \delta$  with  $I_{M}$  defined as peak current,  $I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_{M} \times \sqrt{\delta}$  with  $I_{RMS}$  defined as RMS current.

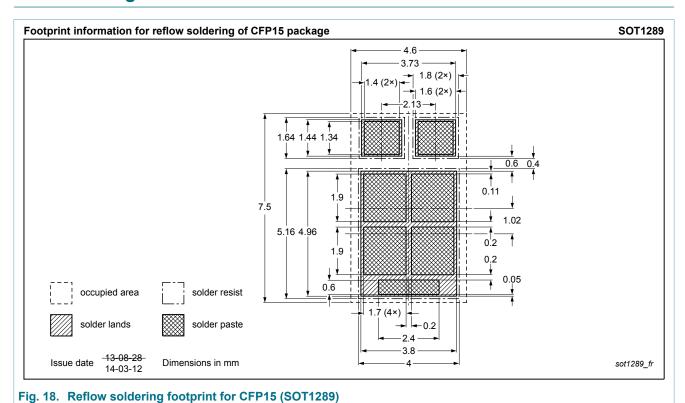
### **Quality information**

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

## 12. Package outline



## 13. Soldering



## 14. Revision history

#### Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG045V150EPD v.5	20160908	Product data sheet	-	PMEG045V150EPD v.4
Modifications:	<ul><li>Table characteristics</li><li>Figure 4 and 5: upda</li></ul>	s: updated $V_F$ and $I_R$ typicated	cal values	
PMEG045V150EPD v.4	20150122	Product data sheet	-	PMEG045V150EPD v.3
PMEG045V150EPD v.3	20150121	Product data sheet	-	PMEG045V150EPD v.2
PMEG045V150EPD v.2	20140704	Preliminary data sheet	-	PMEG045V150EPD v.1
PMEG045V150EPD v.1	20140519	Objective data sheet	-	-

## 15. Legal information

#### **Data sheet status**

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- Please consult the most recently issued document before initiating or completing a design.
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